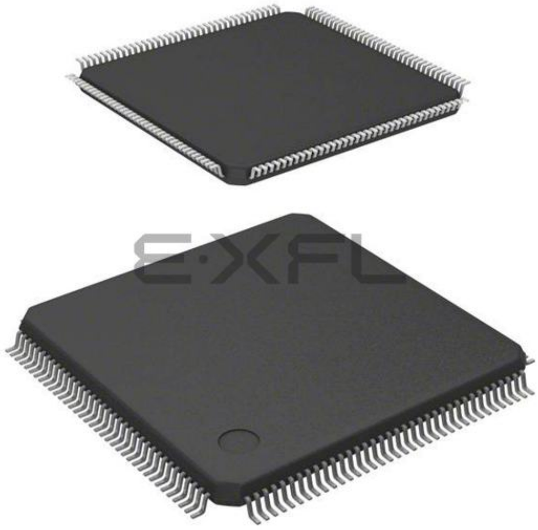
STMicroelectronics - SPC560B54L5C6E0Y Datasheet



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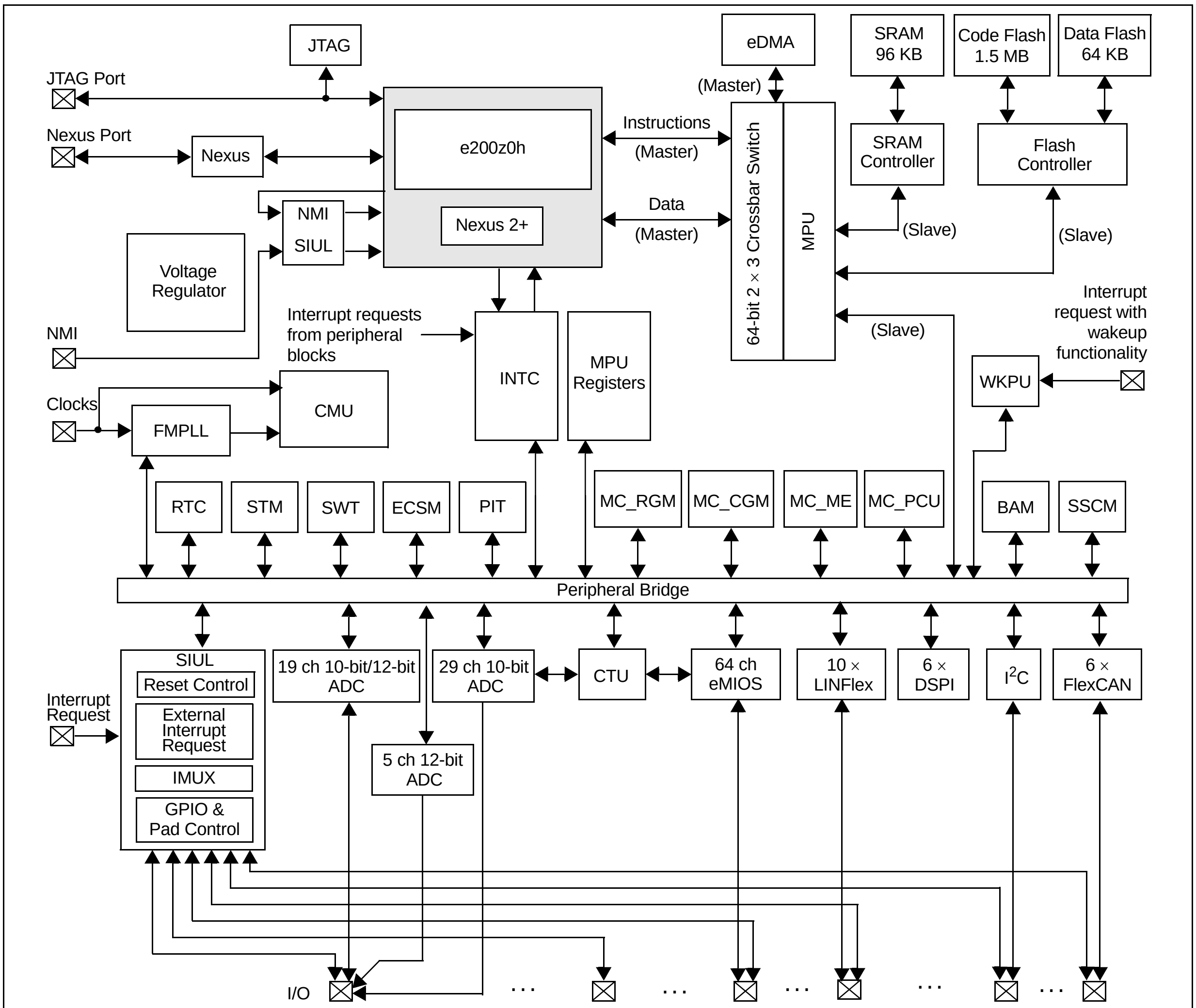
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	e200z0h
Core Size	32-Bit Single-Core
Speed	64MHz
Connectivity	CANbus, I²C, LINbus, SCI, SPI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	121
Program Memory Size	768KB (768K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 53x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/spc560b54l5c6e0y

2 Block diagram

Figure 1 shows a top-level block diagram of the SPC560B54/6x.

Figure 1. SPC560B54/6x block diagram



Legend:

ADC Analog-to-Digital Converter
BAM Boot Assist Module
CMU Clock Monitor Unit
CTU Cross Triggering Unit
DSPIDeserial Serial Peripheral Interface
ECSM Error Correction Status Module
eDMA Enhanced Direct Memory Access
eMIOS Enhanced Modular Input Output System
Flash Flash memory
FlexCAN Controller Area Network
FMPLL Frequency-Modulated Phase-Locked Loop
GPIO General-purpose input/output
I^2C Inter-Integrated Circuit bus
IMUX Internal Multiplexer
INTC Interrupt Controller
JTAG JTAG controller
LINFlex Serial Communication Interface (LIN support)
MC_CGM Clock Generation Module
MC_ME Mode Entry Module
MC_PCU Power Control Unit
MC_RGM Reset Generation Module
MPU Memory Protection Unit
NMI Non-Maskable Interrupt
PIT Periodic Interrupt Timer
RTC Real-Time Clock
SIUL System Integration Unit Lite
SRAM Static Random-Access Memory
SSCM System Status Configuration Module
STM System Timer Module
SWT Software Watchdog Timer
VREG Voltage regulator
WKPU Wakeup Unit
XBAR Crossbar switch

Table 3. SPC560B54/6x series block summary (continued)

Block	Function
Mode entry module (MC_ME)	Provides a mechanism for controlling the device operational mode and mode transition sequences in all functional states; also manages the power control unit, reset generation module and clock generation module, and holds the configuration, control and status registers accessible for applications
Non-maskable interrupt (NMI)	Handles external events that must produce an immediate response, such as power down detection
Periodic interrupt timer (PIT)	Produces periodic interrupts and triggers
Power control unit (MC_PCU)	Reduces the overall power consumption by disconnecting parts of the device from the power supply via a power switching device; device components are grouped into sections called “power domains” which are controlled by the PCU
Real-time counter (RTC)	A free running counter used for time keeping applications, the RTC can be configured to generate an interrupt at a predefined interval independent of the mode of operation (run mode or low-power mode)
Reset generation module (MC_RGM)	Centralizes reset sources and manages the device reset sequence of the device
Static random-access memory (SRAM)	Provides storage for program code, constants, and variables
System integration unit lite (SIUL)	Provides control over all the electrical pad controls and up 32 ports with 16 bits of bidirectional, general-purpose input and output signals and supports up to 32 external interrupts with trigger event configuration
System status and configuration module (SSCM)	Provides system configuration and status data (such as memory size and status, device mode and security status), device identification data, debug status port enable and selection, and bus and peripheral abort enable/disable
System timer module (STM)	Provides a set of output compare events to support AUTOSAR (Automotive Open System Architecture) and operating system tasks
Software watchdog timer (SWT)	Provides protection from runaway code
Wakeup unit (WKPU)	The wakeup unit supports up to 27 external sources that can generate interrupts or wakeup events, of which 1 can cause non-maskable interrupt requests or wakeup events.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
A	PC[8]	PC[13]	PH[15]	PJ[4]	PH[8]	PH[4]	PC[5]	PC[0]	PI[0]	PI[1]	PC[2]	PI[4]	PE[15]	PH[11]	NC	NC	A
B	PC[9]	PB[2]	PH[13]	PC[12]	PE[6]	PH[5]	PC[4]	PH[9]	PH[10]	PI[2]	PC[3]	PG[11]	PG[15]	PG[14]	PA[11]	PA[10]	B
C	PC[14]	VDD_HV	PB[3]	PE[7]	PH[7]	PE[5]	PE[3]	VSS_LV	PC[1]	PI[3]	PA[5]	PI[5]	PE[14]	PE[12]	PA[9]	PA[8]	C
D	PH[14]	PI[6]	PC[15]	PI[7]	PH[6]	PE[4]	PE[2]	VDD_LV	VDD_HV	NC	PA[6]	PH[12]	PG[10]	PF[14]	PE[13]	PA[7]	D
E	PG[4]	PG[5]	PG[3]	PG[2]									PG[1]	PG[0]	PF[15]	VDD_HV	E
F	PE[0]	PA[2]	PA[1]	PE[1]									PH[0]	PH[1]	PH[3]	PH[2]	F
G	PE[9]	PE[8]	PE[10]	PA[0]			VSS_HV	VSS_HV	VSS_HV	VSS_HV			VDD_HV	PI[12]	PI[13]	MSEO	G
H	VSS_HV	PE[11]	VDD_HV	NC			VSS_HV	VSS_HV	VSS_HV	VSS_HV			MDO3	MDO2	MDO0	MDO1	H
J	RESET	VSS_LV	NC	NC			VSS_HV	VSS_HV	VSS_HV	VSS_HV			PI[8]	PI[9]	PI[10]	PI[11]	J
K	EVTI	NC	VDD_BV	VDD_LV			VSS_HV	VSS_HV	VSS_HV	VSS_HV			VDD_HV_ADC1	PG[12]	PA[3]	PG[13]	K
L	PG[9]	PG[8]	NC	EVTO									PB[15]	PD[15]	PD[14]	PB[14]	L
M	PG[7]	PG[6]	PC[10]	PC[11]									PB[13]	PD[13]	PD[12]	PB[12]	M
N	PB[1]	PF[9]	PB[0]	VDD_HV	PJ[0]	PA[4]	VSS_LV	EXTAL	VDD_HV	PF[0]	PF[4]	VSS_HV_ADC1	PB[11]	PD[10]	PD[9]	PD[11]	N
P	PF[8]	PJ[3]	PC[7]	PJ[2]	PJ[1]	PA[14]	VDD_LV	XTAL	PB[10]	PF[1]	PF[5]	PD[0]	PD[3]	VDD_HV_ADC0	PB[6]	PB[7]	P
R	PF[12]	PC[6]	PF[10]	PF[11]	VDD_HV	PA[15]	PA[13]	PI[14]	XTAL32	PF[3]	PF[7]	PD[2]	PD[4]	PD[7]	VSS_HV_ADC0	PB[5]	R
T	NC	NC	NC	MCKO	NC	PF[13]	PA[12]	PI[15]	EXTAL32	PF[2]	PF[6]	PD[1]	PD[5]	PD[6]	PD[8]	PB[4]	T
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	

NOTE: The LBGA208 is available only as development package for Nexus 2+.

NC = Not connected

Figure 5. LBGA208 configuration

3.2 Pad configuration during reset phases

All pads have a fixed configuration under reset.

During the power-up phase, all pads are forced to tristate.

After power-up phase, all pads are tristate with the following exceptions:

- PA[9] (FAB) is pull-down. Without external strong pull-up the device starts fetching from flash.
- PA[8], PC[0] and PH[9:10] are in input weak pull-up when out of reset.
- RESET pad is driven low by the device till 40 FIRC clock cycles after phase2 completion. Minimum phase3 duration is 40 FIRC cycles.
- Nexus output pads (MDO[n], MCKO, EVTO, MSEO) are forced to output.

3.3 Pad configuration during standby mode exit

Pad configuration (input buffer enable, pull enable) for low-power wakeup pads is controlled by both the SIUL and WKPU modules. During standby exit, all low power pads PA[0,1,2,4,15], PB[1,3,8,9,10][a], PC[7,9,11], PD[0,1], PE[0,9,11], PF[9,11,13][b], PG[3,5,7,9][b], PI[1,3][c] are configured according to their respective configuration done in the WKPU module. All other pads will have the same configuration as expected after a reset.

The TDO pad has been moved into the STANDBY domain in order to allow low-power debug handshaking in STANDBY mode. However, no pull-resistor is active on the TDO pad while in STANDBY mode. At this time the pad is configured as an input. When no debugger is connected the TDO pad is floating causing additional current consumption.

To avoid the extra consumption TDO must be connected. An external pull-up resistor in the range of 47–100 kOhms should be added between the TDO pin and VDD. Only if the TDO pin is used as an application pin and a pull-up cannot be used should a pull-down resistor with the same value be used instead between the TDO pin and GND.

3.4 Voltage supply pins

Voltage supply pins are used to provide power to the device. Three dedicated VDD_LV/VSS_LV supply pairs are used for 1.2 V regulator stabilization.

Table 4. Voltage supply pin descriptions

Port pin	Function	Pin number			
		LQFP100	LQFP144	LQFP176	LBGA208
VDD_HV	Digital supply voltage	15, 37, 70, 84	19, 51, 100, 123	6, 27, 59, 85, 124, 151	C2, D9, E16, G13, H3, N4, N9, R5
VSS_HV	Digital ground	14, 16, 35, 69, 83	18, 20, 49, 99, 122	7, 26, 28, 57, 86, 123, 150	G7, G8, G9, G10, H7, H8, H9, H10, J7, J8, J9, J10, K7, K8, K9, K10
VDD_LV	1.2 V decoupling pins. Decoupling capacitor must be connected between these pins and the nearest V_{SS_LV} pin.(1)	19, 32, 85	23, 46, 124	31, 54, 152	D8, K4, P7
VSS_LV	1.2 V decoupling pins. Decoupling capacitor must be connected between these pins and the nearest V_{DD_LV} pin.(1)	18, 33, 86	22, 47, 125	30, 55, 153	C8, J2, N7

a. PB[8, 9] ports have wakeup functionality in all modes except STANDBY.

b. PF[9,11,13], PG[3,5,7,9], PI[1,3] are not available in the 100-pin LQFP.

c. PI[1,3] are not available in the 144-pin LQFP.

Table 4. Voltage supply pin descriptions (continued)

Port pin	Function	Pin number			
		LQFP100	LQFP144	LQFP176	LBGA208
VDD_BV	Internal regulator supply voltage	20	24	32	K3
VSS_HV_ADC0	Reference ground and analog ground for the A/D converter 0 (10-bit)	51	73	89	R15
VDD_HV_ADC0	Reference voltage and analog supply for the A/D converter 0 (10-bit)	52	74	90	P14
VSS_HV_ADC1	Reference ground and analog ground for the A/D converter 1 (12-bit)	59	81	98	N12
VDD_HV_ADC1	Reference voltage and analog supply for the A/D converter 1 (12-bit)	60	82	99	K13

1. A decoupling capacitor must be placed between each of the three VDD_LV/VSS_LV supply pairs to ensure stable voltage (see the recommended operating conditions in the device datasheet).

3.5 Pad types

In the device the following types of pads are available for system pins and functional port pins:

S = Slow[(d)]

M = Medium[(d)] [(e)]

F = Fast[(d)] [(e)]

I = Input only with analog feature[(d)]

J = Input/Output (‘S’ pad) with analog feature

X = Oscillator

3.6 System pins

The system pins are listed in *Table 5*.

d. See the I/O pad electrical characteristics in the chip datasheet for details.

e. All medium and fast pads are in slow configuration by default at reset and can be configured as fast or medium. The only exception is PC[1] which is in medium configuration by default (see the PCR.SRC description in the chip reference manual, Pad Configuration Registers (PCR0–PCR148)).

Table 5. System pin descriptions

Port pin	Function	I/O direction	Pad type	RESET configuration	Pin number			
					LQFP 100	LQFP 144	LQFP 176	LBGA 208(1)
RESET	Bidirectional reset with Schmitt-Trigger characteristics and noise filter.	I/O	M	Input weak pull-up after RGM PHASE2 and 40 FIRC cycles	17	21	29	J1
EXTAL	Analog output of the oscillator amplifier circuit, when the oscillator is not in bypass mode. Analog input for the clock generator when the oscillator is in bypass mode.	I/O	X	Tristate	36	50	58	N8
XTAL	Analog input of the oscillator amplifier circuit. Needs to be grounded if oscillator bypass mode is used.	I	X	Tristate	34	48	56	P8

1. LBGA208 available only as development package for Nexus2+.

3.7 Functional port pins

The functional port pins are listed in *Table 6*.

Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function(1)	Function	Peripheral	I/O direction(2)	Pad type	RESET configuration(3)	Pin number			
								LQFP 100	LQFP 144	LQFP 176	LBGA 208(4)
PB[11]	PCR[27]	AF0 AF1 AF2 AF3 —	GPIO[27] E0UC[3] — CS0_0 ADC0_S[3]	SIUL eMIOS_0 — DSPI_0 ADC_0	I/O I/O — I/O I	J	Tristate	—	—	97	N13
PB[12]	PCR[28]	AF0 AF1 AF2 AF3 —	GPIO[28] E0UC[4] — CS1_0 ADC0_X[0]	SIUL eMIOS_0 — DSPI_0 ADC_0	I/O I/O — O I	J	Tristate	61	83	101	M16
PB[13]	PCR[29]	AF0 AF1 AF2 AF3 —	GPIO[29] E0UC[5] — CS2_0 ADC0_X[1]	SIUL eMIOS_0 — DSPI_0 ADC_0	I/O I/O — O I	J	Tristate	63	85	103	M13
PB[14]	PCR[30]	AF0 AF1 AF2 AF3 —	GPIO[30] E0UC[6] — CS3_0 ADC0_X[2]	SIUL eMIOS_0 — DSPI_0 ADC_0	I/O I/O — O I	J	Tristate	65	87	105	L16
PB[15]	PCR[31]	AF0 AF1 AF2 AF3 —	GPIO[31] E0UC[7] — CS4_0 ADC0_X[3]	SIUL eMIOS_0 — DSPI_0 ADC_0	I/O I/O — O I	J	Tristate	67	89	107	L13

Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function[1]	Function	Peripheral	I/O direction[2]	Pad type	RESET configuration[3]	Pin number			
								LQFP 100	LQFP 144	LQFP 176	LBGA 208[4]
PC[12]	PCR[44]	AF0 AF1 AF2 AF3 — —	GPIO[44] E0UC[12] — — EIRQ[19] SIN_2	SIUL eMIOS_0 — — SIUL DSPI_2	I/O I/O — — I I	M	Tristate	97	141	173	B4
PC[13]	PCR[45]	AF0 AF1 AF2 AF3	GPIO[45] E0UC[13] SOUT_2 —	SIUL eMIOS_0 DSPI_2 —	I/O I/O O —	S	Tristate	98	142	174	A2
PC[14]	PCR[46]	AF0 AF1 AF2 AF3 —	GPIO[46] E0UC[14] SCK_2 — EIRQ[8]	SIUL eMIOS_0 DSPI_2 — SIUL	I/O I/O I/O — I	S	Tristate	3	3	3	C1
PC[15]	PCR[47]	AF0 AF1 AF2 AF3 —	GPIO[47] E0UC[15] CS0_2 — EIRQ[20]	SIUL eMIOS_0 DSPI_2 — SIUL	I/O I/O I/O — I	M	Tristate	4	4	4	D3
Port D											

Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function(1)	Function	Peripheral	I/O direction(2)	Pad type	RESET configuration(3)	Pin number			
								LQFP 100	LQFP 144	LQFP 176	LBGA 208(4)
PF[3]	PCR[83]	AF0 AF1 AF2 AF3 —	GPIO[83] E0UC[13] CS1_2 — ADC0_S[11]	SIUL eMIOS_0 DSPI_2 — ADC_0	I/O I/O O — I	J	Tristate	—	58	66	R10
PF[4]	PCR[84]	AF0 AF1 AF2 AF3 —	GPIO[84] E0UC[14] CS2_2 — ADC0_S[12]	SIUL eMIOS_0 DSPI_2 — ADC_0	I/O I/O O — I	J	Tristate	—	59	67	N11
PF[5]	PCR[85]	AF0 AF1 AF2 AF3 —	GPIO[85] E0UC[22] CS3_2 — ADC0_S[13]	SIUL eMIOS_0 DSPI_2 — ADC_0	I/O I/O O — I	J	Tristate	—	60	68	P11
PF[6]	PCR[86]	AF0 AF1 AF2 AF3 —	GPIO[86] E0UC[23] CS1_1 — ADC0_S[14]	SIUL eMIOS_0 DSPI_1 — ADC_0	I/O I/O O — I	J	Tristate	—	61	69	T11
PF[7]	PCR[87]	AF0 AF1 AF2 AF3 —	GPIO[87] — CS2_1 — ADC0_S[15]	SIUL — DSPI_1 — ADC_0	I/O — O — I	J	Tristate	—	62	70	R11

Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function[1]	Function	Peripheral	I/O direction[2]	Pad type	RESET configuration[3]	Pin number			
								LQFP 100	LQFP 144	LQFP 176	LBGA 208[4]
PG[10]	PCR[106]	AF0 AF1 AF2 AF3 —	GPIO[106] E0UC[24] E1UC[31] — SIN_4	SIUL eMIOS_0 eMIOS_1 — DSPI_4	I/O I/O I/O — I	S	Tristate	—	114	138	D13
PG[11]	PCR[107]	AF0 AF1 AF2 AF3	GPIO[107] E0UC[25] CS0_4 —	SIUL eMIOS_0 DSPI_4 —	I/O I/O I/O —	M	Tristate	—	115	139	B12
PG[12]	PCR[108]	AF0 AF1 AF2 AF3	GPIO[108] E0UC[26] SOUT_4 —	SIUL eMIOS_0 DSPI_4 —	I/O I/O O —	M	Tristate	—	92	116	K14
PG[13]	PCR[109]	AF0 AF1 AF2 AF3	GPIO[109] E0UC[27] SCK_4 —	SIUL eMIOS_0 DSPI_4 —	I/O I/O I/O —	M	Tristate	—	91	115	K16
PG[14]	PCR[110]	AF0 AF1 AF2 AF3	GPIO[110] E1UC[0] LIN8TX —	SIUL eMIOS_1 LINFlex_8 —	I/O I/O O —	S	Tristate	—	110	134	B14

Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function(1)	Function	Peripheral	I/O direction(2)	Pad type	RESET configuration(3)	Pin number			
								LQFP 100	LQFP 144	LQFP 176	LBGA 208(4)
PI[10]	PCR[138]	AF0 AF1 AF2 AF3 —	GPIO[138] — — — ADC0_S[18]	SIUL — — — ADC_0	I/O — — — I	J	Tristate	—	—	110	J15
PI[11]	PCR[139]	AF0 AF1 AF2 AF3 — —	GPIO[139] — — — ADC0_S[19] SIN_3	SIUL — — — ADC_0 DSPI_3	I/O — — — I I	J	Tristate	—	—	111	J16
PI[12]	PCR[140]	AF0 AF1 AF2 AF3 —	GPIO[140] CS0_3 — — ADC0_S[20]	SIUL DSPI_3 — — ADC_0	I/O I/O — — I	J	Tristate	—	—	112	G14
PI[13]	PCR[141]	AF0 AF1 AF2 AF3 —	GPIO[141] CS1_3 — — ADC0_S[21]	SIUL DSPI_3 — — ADC_0	I/O O — — I	J	Tristate	—	—	113	G15

3.8 Nexus 2+ pins

In the LBGA208 package, eight additional debug pins are available (see *Table 7*).

Table 7. Nexus 2+ pin descriptions

Port pin	Function	I/O direction	Pad type	Function after reset	Pin number		
					LQFP 100	LQFP 144	LBGA 208[1]
MCKO	Message clock out	O	F	—	—	—	T4
MDO0	Message data out 0	O	M	—	—	—	H15
MDO1	Message data out 1	O	M	—	—	—	H16
MDO2	Message data out 2	O	M	—	—	—	H14
MDO3	Message data out 3	O	M	—	—	—	H13
EVTI	Event in	I	M	Pull-up	—	—	K1
EVTO	Event out	O	M	—	—	—	L4
MSEO	Message start/end out	O	M	—	—	—	G16

1. LBGA208 available only as development package for Nexus2+.

4 Electrical characteristics

This section contains electrical characteristics of the device as well as temperature and power considerations.

This product contains devices to protect the inputs against damage due to high static voltages. However, it is advisable to take precautions to avoid application of any voltage higher than the specified maximum rated voltages.

To enhance reliability, unused inputs can be driven to an appropriate logic voltage level (V_{DD} or V_{SS}). This could be done by the internal pull-up and pull-down, which is provided by the product for most general purpose pins.

The parameters listed in the following tables represent the characteristics of the device and its demands on the system.

In the tables where the device logic provides signals with their respective timing characteristics, the symbol “CC” for Controller Characteristics is included in the Symbol column.

In the tables where the external system must provide signals with their respective timing characteristics to the device, the symbol “SR” for System Requirement is included in the Symbol column.

4.1 Parameter classification

The electrical parameters shown in this supplement are guaranteed by various methods. To give the customer a better understanding, the classifications listed in *Table 8* are used and the parameters are tagged accordingly in the tables where appropriate.

Table 8. Parameter classifications

Classification tag	Tag description
P	Those parameters are guaranteed during production testing on each individual device.
C	Those parameters are achieved by the design characterization by measuring a statistically relevant sample size across process variations.
T	Those parameters are achieved by design characterization on a small sample size from typical devices under typical conditions unless otherwise noted. All values shown in the typical column are within this category.
D	Those parameters are derived mainly from simulations.

Note: The classification is shown in the column labeled “C” in the parameter tables where appropriate.

4.2 NVUSRO register

Bit values in the Non-Volatile User Options (NVUSRO) Register control portions of the device configuration, namely electrical parameters such as high voltage supply and oscillator margin, as well as digital functionality (watchdog enable/disable after reset).

Table 24. I/O weight(1) (continued)

Supply segment			Pad	LQFP176				LQFP144/100			
				Weight 5 V		Weight 3.3 V		Weight 5 V		Weight 3.3 V	
LQFP 176	LQFP 144	LQFP 100		SRC(2) = 0	SRC = 1	SRC = 0	SRC = 1	SRC = 0	SRC = 1	SRC = 0	SRC = 1
4	2	2	PD[8]	1%	—	1%	—	1%	—	2%	—
			PB[4]	1%	—	1%	—	1%	—	2%	—
			PB[5]	1%	—	1%	—	1%	—	2%	—
			PB[6]	1%	—	1%	—	1%	—	2%	—
			PB[7]	1%	—	1%	—	1%	—	2%	—
			PD[9]	1%	—	1%	—	1%	—	2%	—
			PD[10]	1%	—	1%	—	1%	—	2%	—
			PD[11]	1%	—	1%	—	1%	—	2%	—

The internal voltage regulator requires external capacitance (C_{REGn}) to be connected to the device in order to provide a stable low voltage digital supply to the device. Capacitances should be placed on the board as near as possible to the associated pins. Care should also be taken to limit the serial inductance of the board to less than 5 nH.

Each decoupling capacitor must be placed between each of the three V_{DD_LV}/V_{SS_LV} supply pairs to ensure stable voltage (see *Section 4.4: Recommended operating conditions*).

Table 26. Voltage regulator electrical characteristics

Symbol		C	Parameter	Conditions[1]	Value			Unit
					Min	Typ	Max	
C_{REGn}	SR	—	Internal voltage regulator external capacitance	—	200	—	500	nF
R_{REG}	SR	—	Stability capacitor equivalent serial resistance	Range: 10 kHz to 20 MHz	—	—	0.2	W
C_{DEC1}	SR	—	Decoupling capacitance[2] ballast	V_{DD_BV}/V_{SS_LV} pair: V_{DD_BV} = 4.5 V to 5.5 V	100[3]	470[4]	—	nF
				V_{DD_BV}/V_{SS_LV} pair: V_{DD_BV} = 3 V to 3.6 V	400		—	
C_{DEC2}	SR	—	Decoupling capacitance regulator supply	V_{DD}/V_{SS} pair	10	100	—	nF
V_{MREG}	CC	T	Main regulator output voltage	Before exiting from reset	—	1.32	—	V
		P		After trimming	1.16	1.28	—	
I_{MREG}	SR	—	Main regulator current provided to V_{DD_LV} domain	—	—	—	150	mA
$I_{MREGINT}$	CC	D	Main regulator module current consumption	I_{MREG} = 200 mA	—	—	2	mA
				I_{MREG} = 0 mA	—	—	1	
V_{LPREG}	CC	P	Low-power regulator output voltage	After trimming	1.16	1.28	—	V
I_{LPREG}	SR	—	Low-power regulator current provided to V_{DD_LV} domain	—	—	—	15	mA
$I_{LPREGINT}$	CC	D	Low-power regulator module current consumption	I_{LPREG} = 15 mA; T_A = 55 °C	—	—	600	µA
		—		I_{LPREG} = 0 mA; T_A = 55 °C	—	5	—	
V_{ULPREG}	CC	P	Ultra low power regulator output voltage	After trimming	1.16	1.28	—	V
I_{ULPREG}	SR	—	Ultra low power regulator current provided to V_{DD_LV} domain	—	—	—	5	mA
$I_{ULPREGINT}$	CC	D	Ultra low power regulator module current consumption	I_{ULPREG} = 5 mA; T_A = 55 °C	—	—	100	µA
				I_{ULPREG} = 0 mA; T_A = 55 °C	—	2	—	
I_{DD_BV}	CC	D	In-rush average current on V_{DD_BV} during power-up[5]	—	—	—	300[6]	mA

Table 42. Fast internal RC oscillator (16 MHz) electrical characteristics (continued)

Symbol		C	Parameter	Conditions(1)		Value Min	Value Typ	Value Max	Unit
$I_{FIRCSTOP}$	CC	T	Fast internal RC oscillator high frequency and system clock current in stop mode	T_A = 25 °C	sysclk = off	—	500	—	µA
					sysclk = 2 MHz	—	600	—	
					sysclk = 4 MHz	—	700	—	
					sysclk = 8 MHz	—	900	—	
					sysclk = 16 MHz	—	1250	—	
t_{FIRCSU}	CC	C	Fast internal RC oscillator start-up time	V_{DD} = 5.0 V ± 10%		—	1.1	2.0	µs
$\Delta_{FIRCPRE}$	CC	C	Fast internal RC oscillator precision after software trimming of f_{FIRC}	T_A = 25 °C		–1	—	1	%
$\Delta_{FIRCTRIM}$	CC	C	Fast internal RC oscillator trimming step	T_A = 25 °C		—	1.6		%
$\Delta_{FIRCVAR}$	CC	C	Fast internal RC oscillator variation over temperature and supply with respect to f_{FIRC} at T_A = 25 °C in high-frequency configuration	—		–5	—	5	%

1. V_{DD} = 3.3 V ± 10% / 5.0 V ± 10%, T_A = –40 to 125 °C, unless otherwise specified.
2. This does not include consumption linked to clock tree toggling and peripherals consumption when RC oscillator is ON.

4.16 Slow internal RC oscillator (128 kHz) electrical characteristics

The device provides a 128 kHz low power internal RC oscillator. This can be used as the reference clock for the RTC module.

Table 43. Slow internal RC oscillator (128 kHz) electrical characteristics

Symbol		C	Parameter	Conditions(1)	Value Min	Value Typ	Value Max	Unit
f_{SIRC}	CC	P	Slow internal RC oscillator low frequency	T_A = 25 °C, trimmed	—	128	—	kHz
	SR	—		—	100	—	150	
I_{SIRC}(2)	CC	C	Slow internal RC oscillator low frequency current	T_A = 25 °C, trimmed	—	—	5	µA
t_{SIRCSU}	CC	P	Slow internal RC oscillator start-up time	T_A = 25 °C, V_{DD} = 5.0 V ± 10%	—	8	12	µs

Equation 14 ADC_1 (12-bit)

$$C_F > 8192 \bullet C_S$$

4.17.3 ADC electrical characteristics

Table 44. ADC input leakage current

Symbol		C	Parameter	Conditions		Value Min	Typ	Max	Unit
I_{LKG}	CC	D	Input leakage current	T_A = –40 °C	No current injection on adjacent pin	—	1	70	nA
		D		T_A = 25 °C		—	1	70	
		D		T_A = 85 °C			3	100	
		D		T_A = 105 °C		—	8	200	
		P		T_A = 125 °C		—	45	400	

Table 45. ADC_0 conversion characteristics (10-bit ADC_0)

Symbol		C	Parameter	Conditions[1]	Value Min	Typ	Max	Unit
V_{SS_ADC0}	SR	—	Voltage on VSS_HV_ADC0 (ADC_0 reference) pin with respect to ground (V_{SS})[2]	—	–0.1	—	0.1	V
V_{DD_ADC0}	SR	—	Voltage on VDD_HV_ADC pin (ADC reference) with respect to ground (V_{SS})	—	V_{DD} – 0.1	—	V_{DD} + 0.1	V
V_{AINx}	SR	—	Analog input voltage[3]	—	V_{SS_ADC0} – 0.1	—	V_{DD_ADC0} + 0.1	V
$I_{ADC0pwd}$	SR	—	ADC_0 consumption in power down mode	—	—	—	50	µA
$I_{ADC0run}$	SR	—	ADC_0 consumption in running mode	—	—	—	5	mA
f_{ADC0}	SR	—	ADC_0 analog frequency	—	6	—	32 + 4%	MHz
Δ_{ADC0_SYS}	SR	—	ADC_0 digital clock duty cycle (ipg_clk)	ADCLKSEL = 1[4]	45	—	55	%
t_{ADC0_PU}	SR	—	ADC_0 power up delay	—	—	—	1.5	µs
t_{ADC0_S}	CC	T	Sampling time[5]	f_{ADC} = 32 MHz, INPSAMP = 17	0.5	—		µs
				f_{ADC} = 6 MHz, INPSAMP = 255	—	—	42	
t_{ADC0_C}	CC	P	Conversion time[6]	f_{ADC} = 32 MHz, INPCMP = 2	0.625	—	—	µs
C_S	CC	D	ADC_0 input sampling capacitance	—	—	—	3	pF

5.2.2 LQFP144

Figure 34. LQFP144 package mechanical drawing

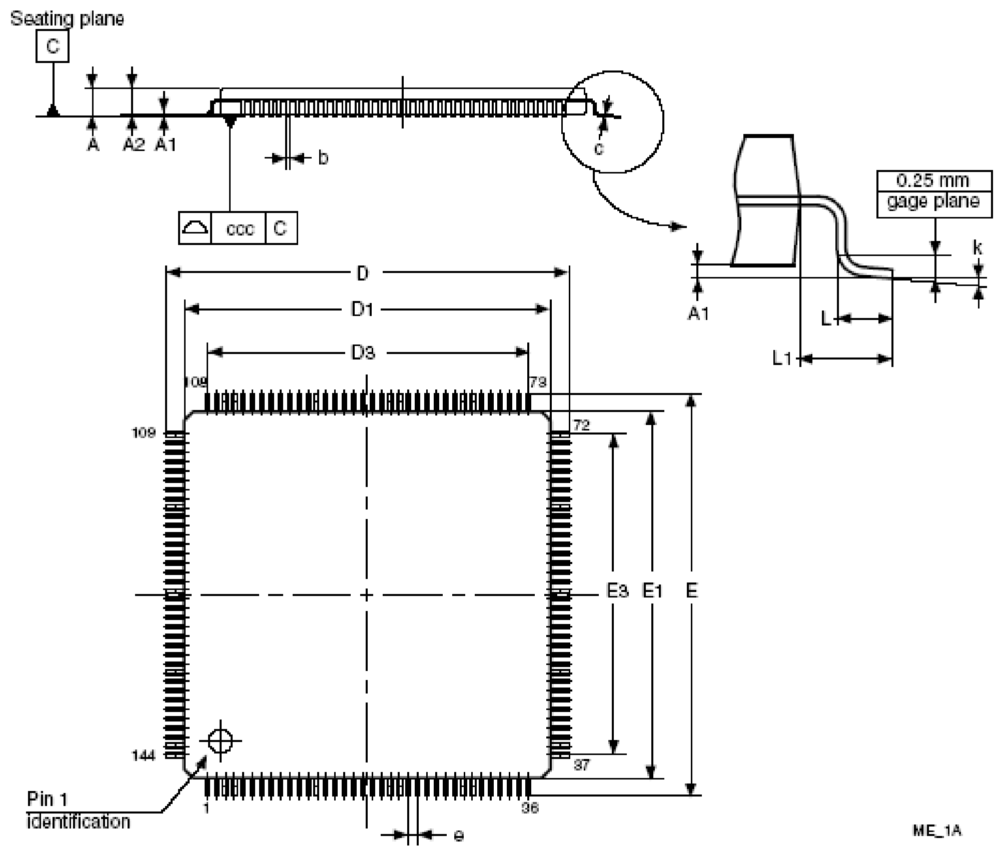
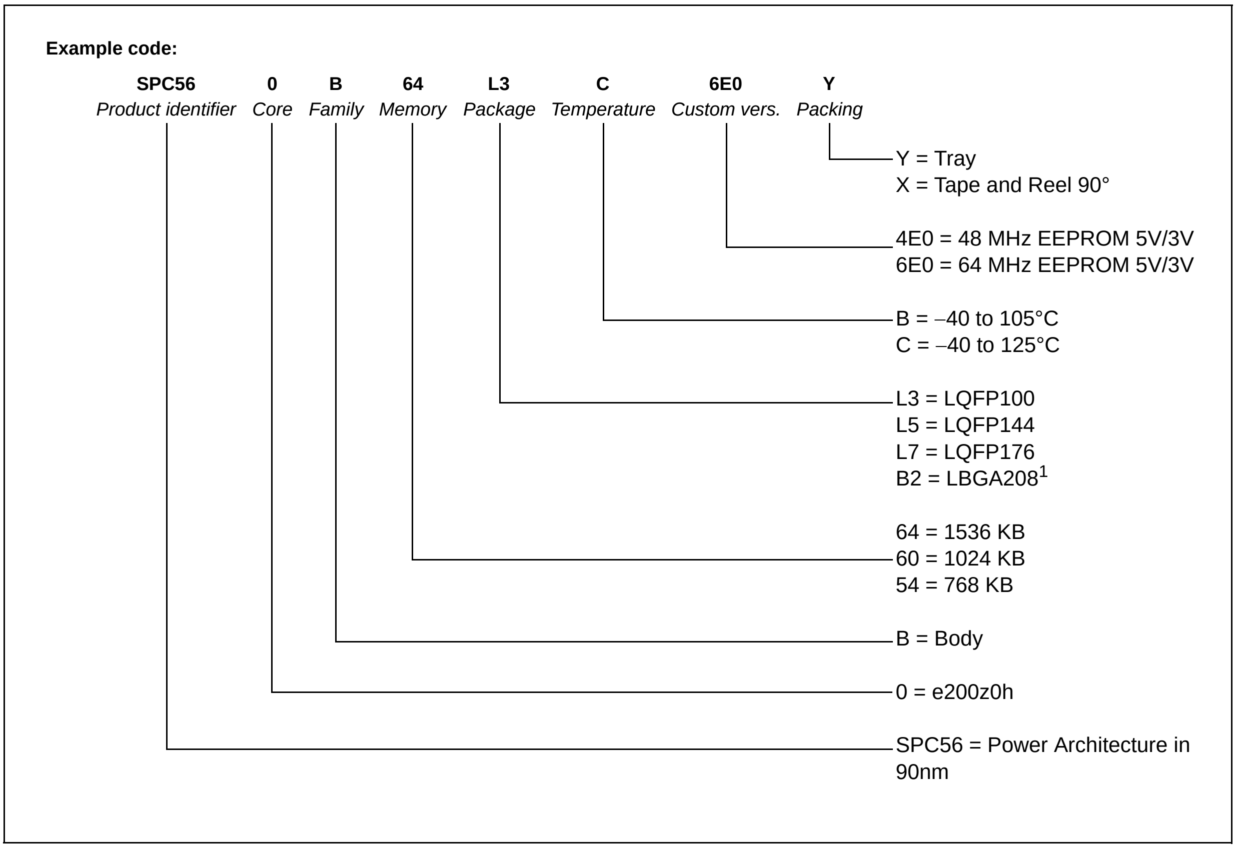


Table 52. LQFP144 mechanical data

Symbol	mm			inches(1)		
	Min	Typ	Max	Min	Typ	Max
A	—	—	1.600	—	—	0.0630
A1	0.050	—	0.150	0.0020	—	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	—	0.200	0.0035	—	0.0079
D	21.800	22.000	22.200	0.8583	0.8661	0.8740

6 Ordering information

Figure 37. Commercial product code structure



1. LBGA208 is available only as development package for Nexus2+.

Table 56. Revision history (continued)

Date	Revision	Changes
12-Sep- 2011 (continued)	6 (continued)	Section “Program/erase characteristics”: removed table “FLASH_BIU settings vs. frequency of operation” and associated introduction “Program and erase specifications” table: updated symbols PFCRn settings vs. frequency of operation: replaced “FLASH_BIU” with “PFCRn” in table title; updated field names and frequencies “Flash power supply DC electrical characteristics” table: deleted footnote 2 Crystal oscillator and resonator connection scheme: inserted footnote about possibly requiring a series resistor Fast external crystal oscillator (4 to 16 MHz) electrical characteristics: updated parameter classification for $V_{FXOSCOP}$ Slow external crystal oscillator (32 kHz) electrical characteristics: updated footnote 1 Section “ADC electrical characteristics”: updated symbols for offset error and gain error Section “Input impedance and ADC accuracy”: changed “V_A/V_{A2}” to “V_{A2}/V_A” in Equation 11 ADC input leakage current: updated I_{LKG} characteristics ADC_0 conversion characteristics table: replaced instances of “ADCx_conf_sample_input” with “INPSAMP”; replaced instances of “ADCx_conf_comp” with “INPCMP ADC_1 characteristic and error definitions: replaced “AVDD” with “V_{DD_ADC}” ADC_1 conversion characteristics table: replaced instances of “ADCx_conf_sample_input” with “INPSAMP”; replaced instances of “ADCx_conf_comp” with “INPCMP” Updated “On-chip peripherals current consumption” table Removed order codes tables.
18-Sep-2013	7	Updated Disclaimer.
05-May-2014	8	*Table 13: Recommended operating conditions (3.3 V)*, added minimum value of T_{VDD} and footnote about it. *Table 14: Recommended operating conditions (5.0 V)*, added minimum value of T_{VDD} and footnote about it. *Table 21: Output pin transition times*, replaced T_{tr} with t_{tr} *Table 25: Reset electrical characteristics*, replaced T_{tr} with t_{tr} Updated *Section 4.17.2: Input impedance and ADC accuracy* *Table 27: Low voltage detector electrical characteristics*, changed $V_{LVDHV3L}$(min) and $V_{LVDHV3BL}$(min) from 2.7 V to 2.6 V. *Table 29: Program and erase specifications*, added footnote about t_{ESRT} *Table 41: FMPLL electrical characteristics*, deleted footnote relative to maximum value of f_{CPU} *Table 45: ADC_0 conversion characteristics (10-bit ADC_0)*, changed $I_{ADC0run}$ value from 40 mA to 5 mA. *Table 48: DSPI characteristics*, in the heading row, replaced DSPI0/DSPI1/DSPI5/DSPI6 with DSPI0/DSPI1/DSPI3/DSPI5.
22-Jan-2016	9	In *Table 1: Device summary*, added SPC560B64L3 for 1.5 MB code flash devices. In *Table 2: SPC560B54/6x family comparison*, added column relating to “LQFP100” package in SPC560B64 devices. In *Table 28: Power consumption on VDD_BV and VDD_HV*: – changed footnote 2 “Running consumption does not include I/Os...” to “I_{DDMAX} is drawn only from the VDD_BV pin. Running consumption does not include I/Os...” – changed footnote 4 “RUN current measured with...” to “I_{DDRUN} is drawn only from the VDD_BV pin. RUN current measured with...”